

TRILITE® UPHR1

H₂O₂ Removal

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TRILITE® UPHR1 is a product for the removal of hydrogen peroxide (H₂O₂) and anions generated by TOC-UV treatment and is used to stabilize and extend the lifespan of the polishing system in the post-polishing stage of the semiconductor ultrapure water process.

Physical and Chemical Properties

	SAC	SBA
Matrix	Styrene-DVB, Gel	
Functional group	H ⁺	OH ⁻
Ionic form	1.9	1.0
Particle Size(μm)	660±50	630±50
Uniformity coefficient	1.1 ↓	1.1 ↓
Ionic Conversion(%)	H ⁺	99.0 Min
	OH ⁻	95.0 Min
	Cl ⁻	1.0 Max
Inlet condition	Ultrapure water, Resistivity>18.2MΩ·cm, TOC<1ppb, SV10	
Outlet condition	Guaranteed 18.2 MΩ·cm ↑ (in 24hr.)	

Recommended Operating Conditions

Operating Temp(°C)	60	pH Range	0~14
Bed Depth(mm)	600	Service Flow Rate(m/h)	5~60

Applications

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info@lennotech.com Tel. +31-152-610-900
www.lennotech.com Fax. +31-152-616-289